



2F AgCu/4J29(4J42)cd>?erW\ ] j k ( 6789523} ~•: ; <  
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AgCu t ?Y) \* +, +tu- ng. /O+w\$%1 2P34{ \* |

AgCu/4J29(4J42) is used as lead frame of IC packaged with ceramic and the crystal oscillators. Through the AgCu solder, we can realize packaging of lead frame 4J29 (4J42) and the metalized ceramic, could solve the dieattach of AgCu solder chip side-firing to improve the welding efficiency meet the highest of automated die attach

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%LRDF B8DF eJ 5pq: r D. { \* `

Not only possess stainless steel s strength, processability and corrosion resistance, the  
clad layer Cu or Ni also possess the feature of corrosion resistance, conductivity,  
strength and deep stamp possibility.

**6789: 2; \$%&' ( Clad metal for semiconductor<s support&retardmppn. ;**